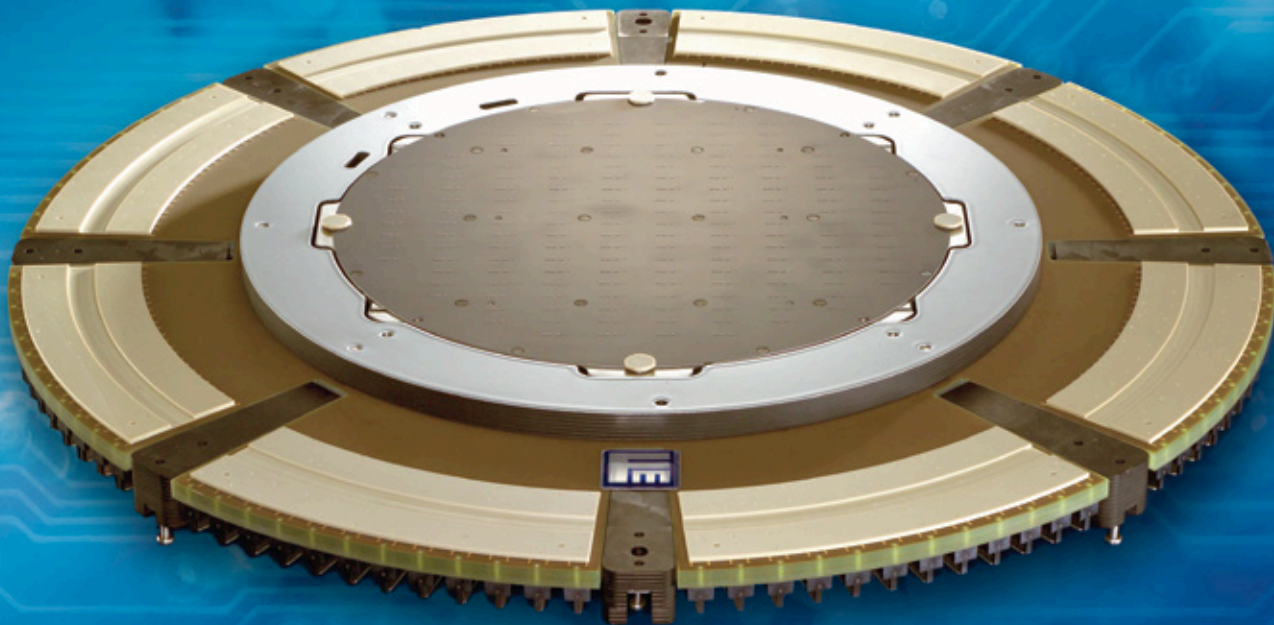


ViProbe® XXL 200

Wafer Test Probecard



FEINMETALL

Contact technologies for electronics

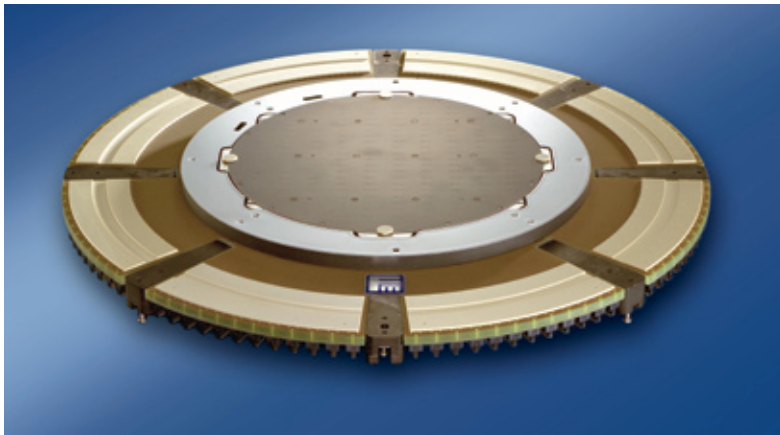


ViProbe® XXL 200

FEINMETALL ViProbe® XXL-Series represents the leading technology in high parallel wafer probing. Our ViProbe® Type XXL 200 is designed for a 1- or 2- touch-down solution at 200 mm wafer. Major application is for memory wafer test or other advanced multiple DIE test applica-

tion. ViProbe® XXL products are based on Direct Attach ViProbe® Technology and currently available for pad pitches down to 80 µm.

ViProbe® XXL products provide the capability for substantial time- and cost-savings in wafer testing.



- Memory Chip Application
- High Parallel Probing
- Active Area Ø 200 mm
- up to 25.000 Test Points
- min. Pad Pitch 80 µm
- 2.5 MIL Beam
- Contact Force ~ 6,5 cN / BEAM
- Low Contact Force ~ 5,5 cN / BEAM
- Tester : Advantest 5375 / 5377, Verigy 5400
- Prober: TSK UF 3000, TEL P8/P12

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